
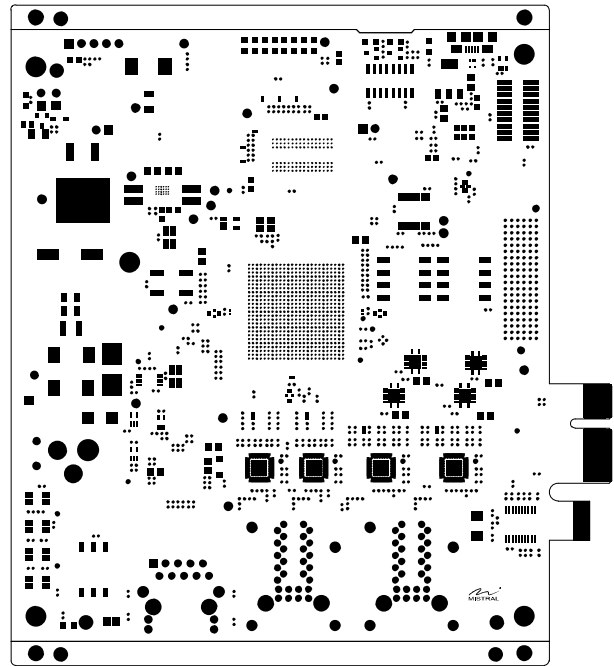

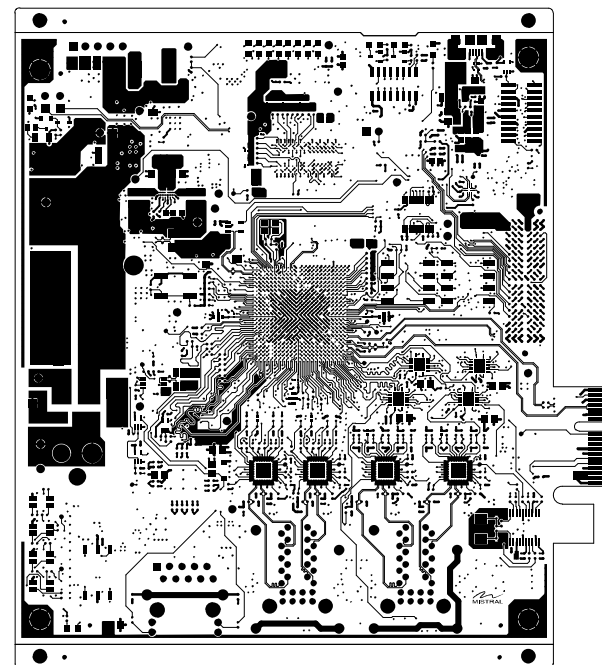



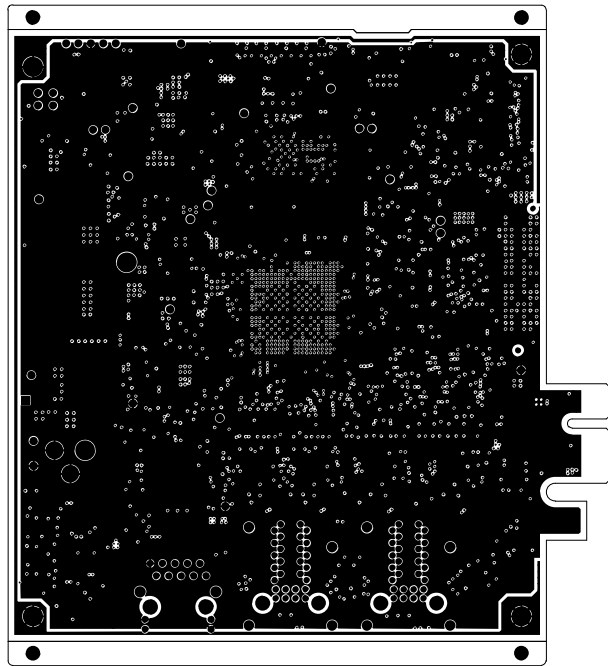
<div> MISTRAL SOLUTIONS.PVT.LTD, #60, ADARSH REGENT, 100'FT RING ROAD, DOMLUR EXTENSION, BANGALORE-560 071</div>		
TITLE: K2G ICE 3N0003 PCB	REV 1.00	SCALE: 1
DATE: 03MAR17 PRIMARY-PASTEMASK	SHEET 14 OF 15	




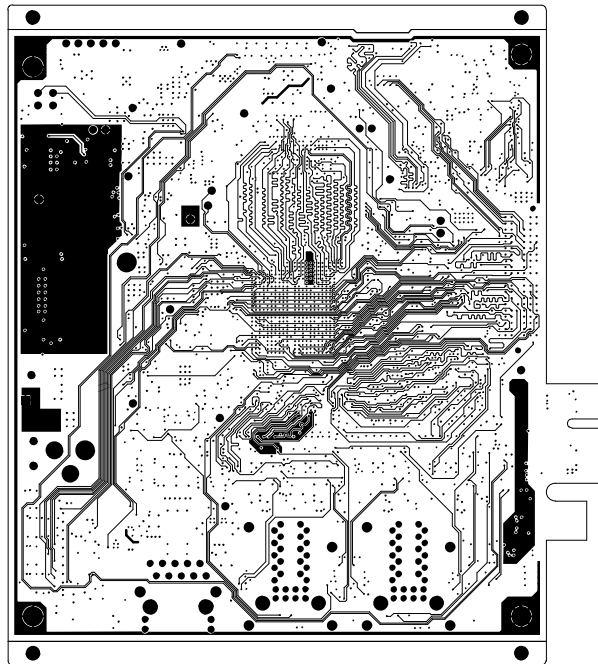
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TITLE: K2G ICE 3N0003 PCB	REV 1.00	SCALE: 1
DATE: 03MAR17	PRIMARY-SOLDERMASK	SHEET 03 OF 15




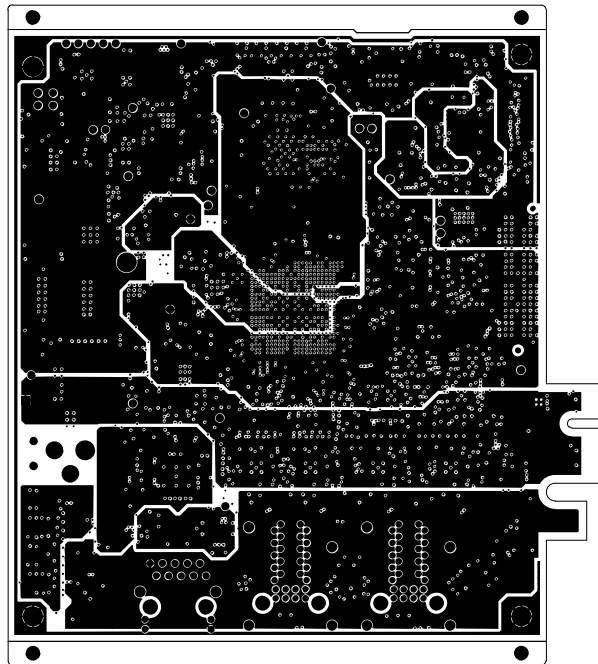
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TITLE: K2G ICE 3N0003 PCB	REV 1.00	SCALE: 1
DATE: 03MAR17 PRIMARY-SIDE-SIG	SHEET 04 OF 15	




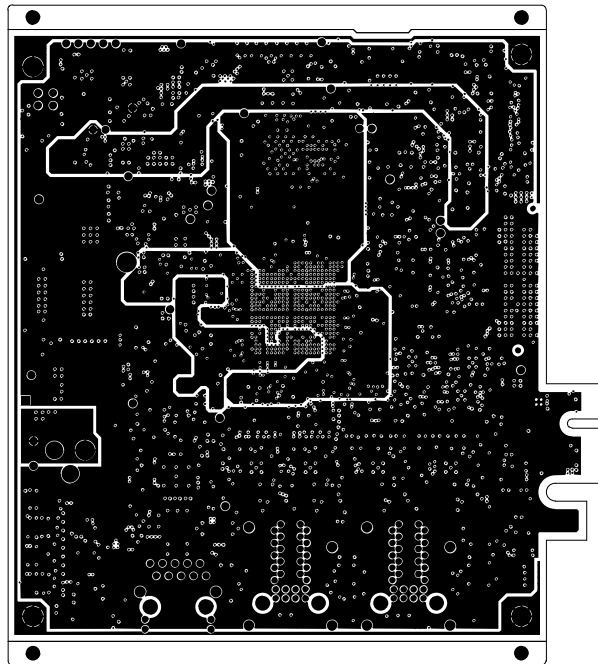
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TITLE: K2G ICE 3N0003 PCB	REV 1.00	SCALE: 1
DATE: 03MAR17	GROUND-PLANE-01	SHEET 05 OF 15




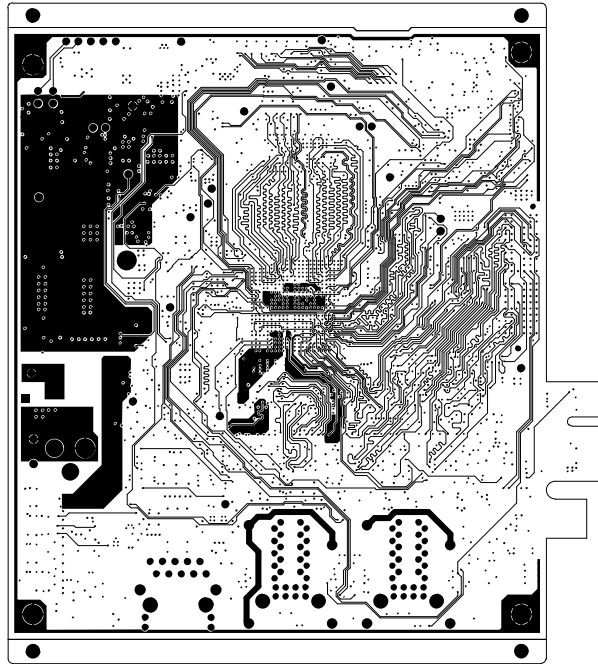
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TITLE: K2G ICE 3N0003 PCB	REV 1.00	SCALE: 1
DATE: 03MAR17	INNER-SIGNAL-01	SHEET 06 OF 15




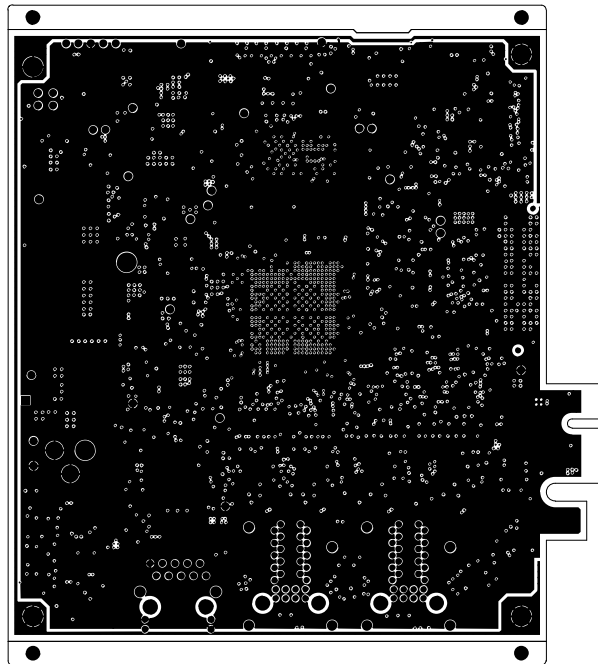
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TITLE: K2G ICE 3N0003 PCB	REV 1.00	SCALE: 1
DATE: 03MAR17 POWER-PLANE-01	SHEET 07 OF 15	




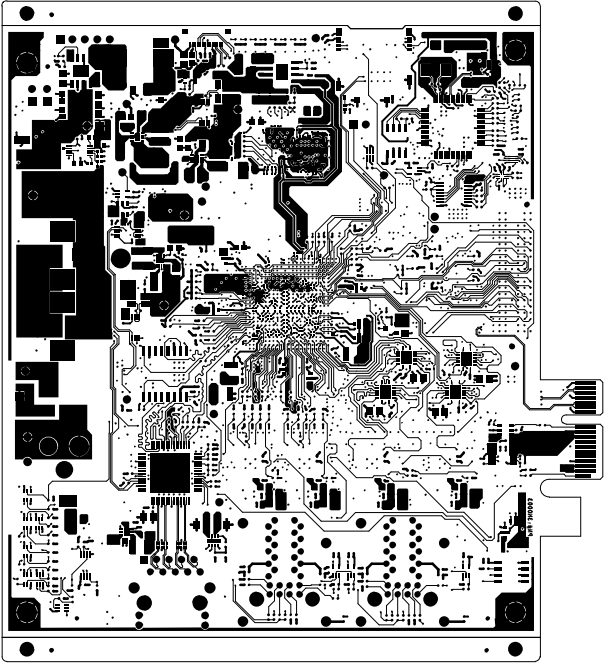
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TITLE: K2G ICE 3N0003 PCB	REV 1.00	SCALE: 1
DATE: 03MAR17 POWER-PLANE-02	SHEET 08 OF 15	




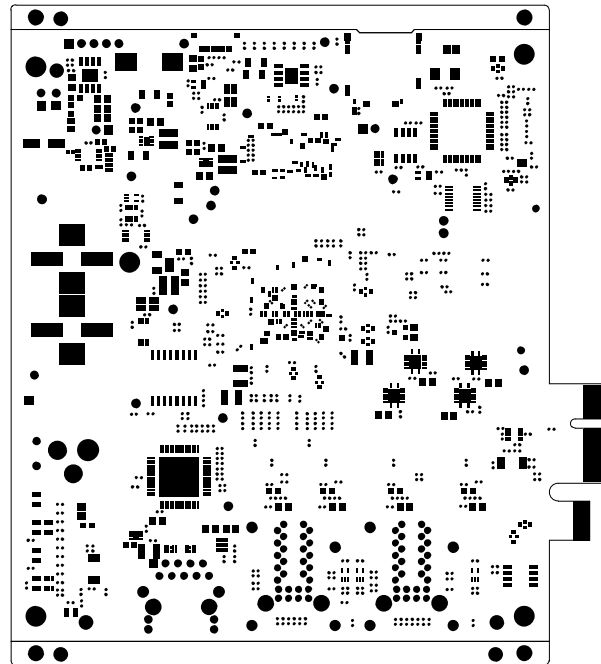
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TITLE: K2G ICE 3N0003 PCB	REV 1.00	SCALE: 1
DATE: 03MAR17	INNER-SIGNAL-02	SHEET 09 OF 15




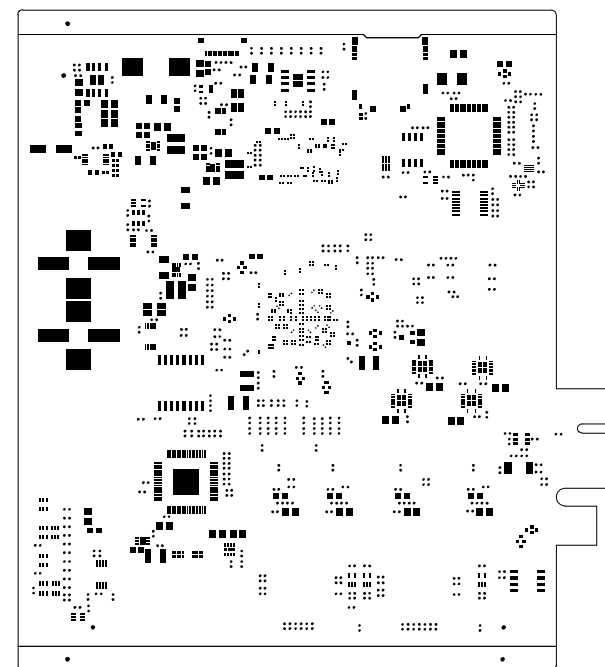
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TITLE: K2G ICE 3N0003 PCB	REV 1.00	SCALE: 1
DATE: 03MAR17	GROUND-PLANE-02	SHEET 10 OF 15




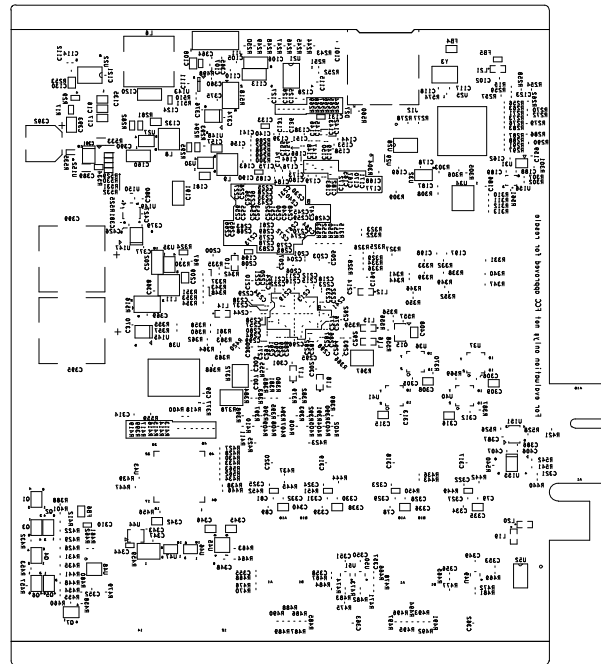
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TITLE: K2G ICE 3N0003 PCB	REV 1.00	SCALE: 1
DATE: 03MAR17	SECONDARY-SIDE-SIG	SHEET 11 OF 15




<div><div>MISTRAL</div><div>MISTRAL SOLUTIONS.PVT.LTD, #60, ADARSH REGENT, 100'FT RING ROAD, DOMLUR EXTENSION, BANGALORE-560 071</div></div>			
TITLE: K2G ICE 3N0003 PCB	REV 1.00	SCALE: 1	
DATE: 03MAR17	SECONDARY-SOLDERMASK	SHEET	12 OF 15



 MISTRAL SOLUTIONS.PVT.LTD, #60, ADARSH REGENT, 100'FT RING ROAD, DOMLUR EXTENSION, BANGALORE-560 071		
TITLE: K2G ICE 3N0003 PCB	REV 1.00	SCALE: 1
DATE: 03MAR17	SECONDARY-PASTEMASK	SHEET 15 OF 15



 MISTRAL SOLUTIONS.PVT.LTD, #60, ADARSH REGENT, 100'FT RING ROAD, DOMLUR EXTENSION, BANGALORE-560 071		
TITLE: K2G ICE 3N0003 PCB	REV 1.0D	SCALE: 1
DATE: 03MAR17	SECONDARY-SILKSCREEN	SHEET 13 OF 15

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
.	10.0	+2.0/-2.0	PLATED	2819
•	35.0	+3.0/-3.0	PLATED	66
•	40.0	+2.0/-2.0	PLATED	13
•	40.0	+3.0/-3.0	PLATED	22
⊠	42.0	+3.0/-3.0	PLATED	2
•	50.0	+3.0/-3.0	PLATED	2
▲	62.99	+3.0/-3.0	PLATED	8
•	67.0	+3.0/-3.0	PLATED	2
⊙	120.0	+3.0/-3.0	PLATED	2
⊙	138.0	+3.0/-3.0	PLATED	5
⊙	140.0	+3.0/-3.0	PLATED	1
⊙	50.0	+2.0/-2.0	NON-PLATED	2
⊠	122.05	+2.0/-2.0	NON-PLATED	4
⊠	125.98	+2.0/-2.0	NON-PLATED	2
⊠	126.0	+3.0/-3.0	NON-PLATED	4

FAB NOTES:

- ALL DIMENSIONS ARE IN INCHES, UNLESS OTHERWISE NOTED.
- THE PWB SHALL BE FABRICATED TO IPC-6012, CLASS 2 AND WORKMANSHIP SHALL CONFORM TO IPC-A-600, CLASS 2. CURRENT REVISIONS.
- BOARD MATERIAL SHALL BE IT180A OR EQUIVALENT, RoHS COMPLIANT AND LEAD FREE ASSEMBLY CAPABLE. BOARD MATERIAL SHALL MEET OR EXCEED IPC-4101B. COLOR: NATURAL.
- BOARD MATERIAL & CONSTRUCTION TO BE UL94V0 CERTIFIED AND MARKED ON TOP SIDE OF FINISHED BOARD.
- MINIMUM COPPER WALL THICKNESS OF PLATED-THRU HOLES TO BE .001 INCH, WITH A MINIMUM ANNULAR RING OF .002 INCH.
- OVERALL BOARD THICKNESS TO BE .0625 +/- 10% AND APPLIES AFTER ALL LAMINATION AND PLATING PROCESSES, MEASURED FROM COPPER TO COPPER.
- MAX. WARP & TWIST TO BE .0075 INCHES PER INCH.
- BOARD MUST BE ELECTRICALLY TESTED USING SUPPLIED IPC-D-356 NETLIST.
- ALL VIAS TO HAVE SOLDERMASK. VIAS ON THE PADS SHALL BE MASK OPENED.
- ALL UNCONNECTED VIA/PADS SHALL BE SUPPRESSED IN THE INTERNAL LAYERS.
- EDGE FINGER SHALL BE PLATED WITH HARD GOLD AS PER IPC 6012 CLASS 2.
- THERE ARE 9 (NINE) INTENTIONAL SHORTS ON THE BOARD.

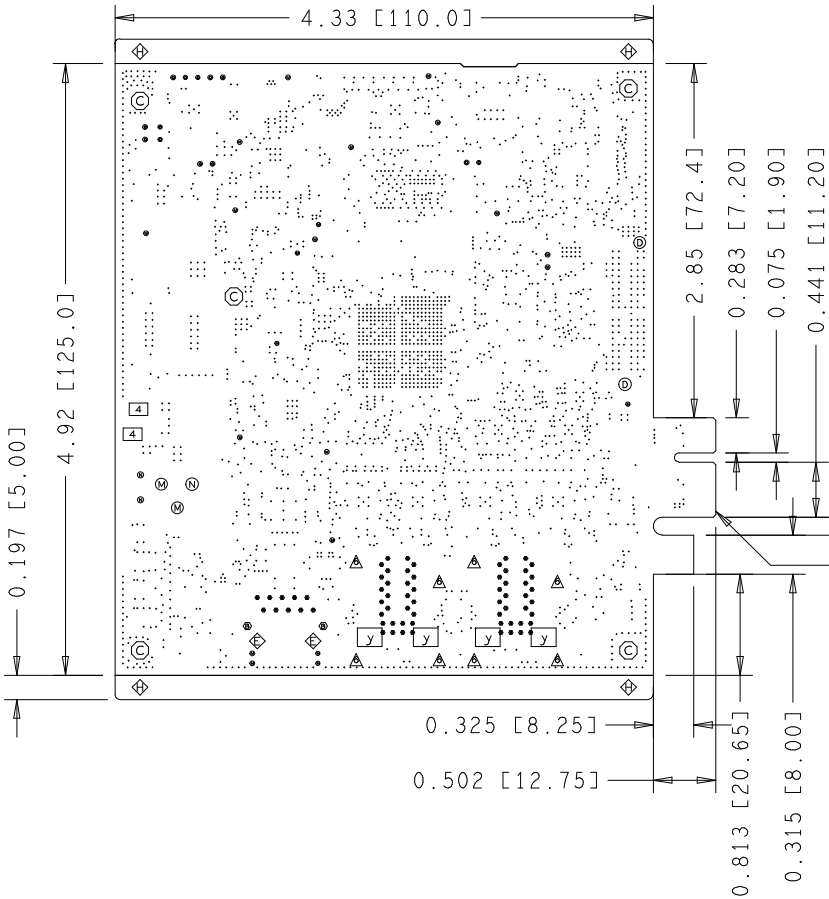
PROCESS NOTES:

- PLATE ALL EXPOSED AREAS WITH ELECTROLESS IMMERSION GOLD, NICKEL 150 MICROINCHES THK MIN GOLD 2-8 MICROINCHES THK MIN.
- APPLY LPI SOLDERMASK OVER BARE COPPER (SMOBC). COLOR: BLACK SOLDERMASK SHALL CONFORM TO IPC-SM-840, CLASS H. CURRENT REV.
- SOLDERMASK ARTWORK HAS ZERO (0) OVERSIZED PADS. FABRICATION VENDOR IS ALLOWED TO ADJUST THE COMPONENT SOLDERMASK PADS TO MEET THEIR TOOLING REQUIREMENTS.
- APPLY LPI SILKSCREEN OR EQUIVALENT PER THE ARTWORK. COLOR: WHITE.

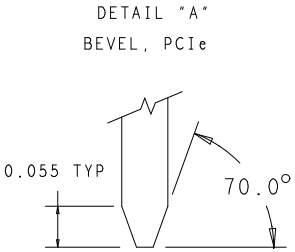
LAYERS	SINGLE-ENDED				EDGE-COUPLED DIFFERENTIAL					
	TRACE WIDTH	TARGET Ohms	TRACE WIDTH	TARGET Ohms	TRACE WIDTH	TRACE SPACE	TARGET Ohms	TRACE WIDTH	TRACE SPACE	TARGET Ohms
	in mils	+/-10%	in mils	+/-10%	in mils	in mils	+/-10%	in mils	in mils	+/-10%
L1_TOP	6.11	50	-	-	4.5	4.5	90	4.0	6.0	100
L3_SIG1	5.5	50	-	-	-	-	-	4.0	8.5	100
L6_SIG2	5.5	50	-	-	-	-	-	4.0	8.5	100
L8_BOTTOM	6.11	50	-	-	4.5	4.5	90	4.0	6.0	100


NOTE :
IMPEDANCE REQUIREMENT :- THIS DESIGN MAY NOT CONTAIN ALL THE FEATURES LISTED IN THE ABOVE TABLE

REV #	DESCRIPTION	DATE
1.0D	PRODUCTION RELEASE	030317



BEVEL SEE DETAIL "A"

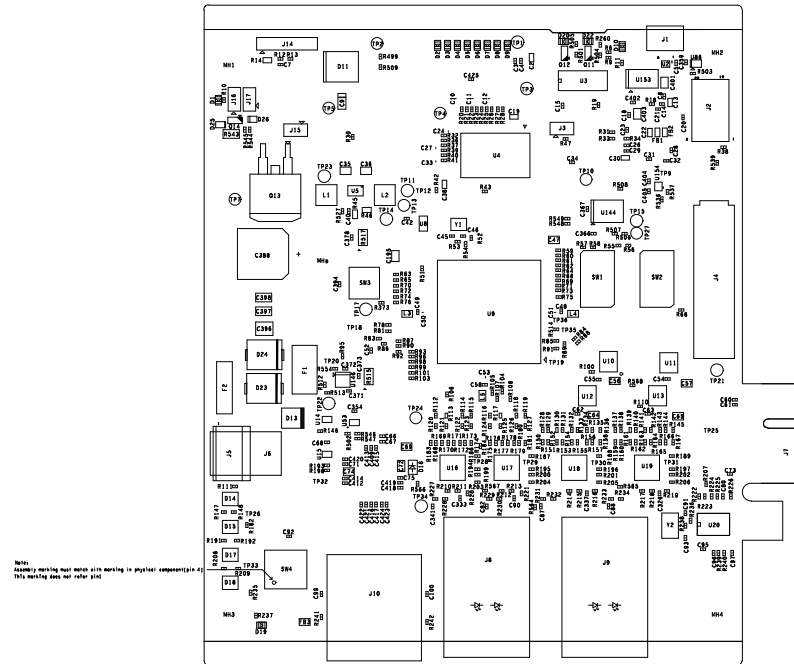


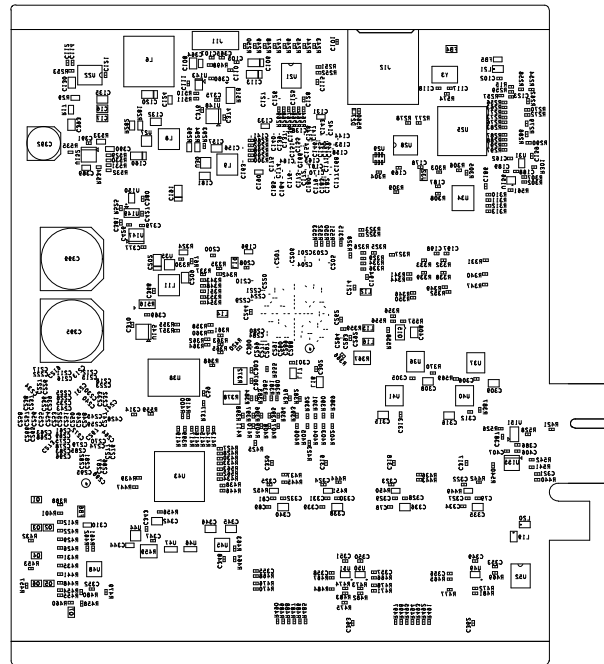


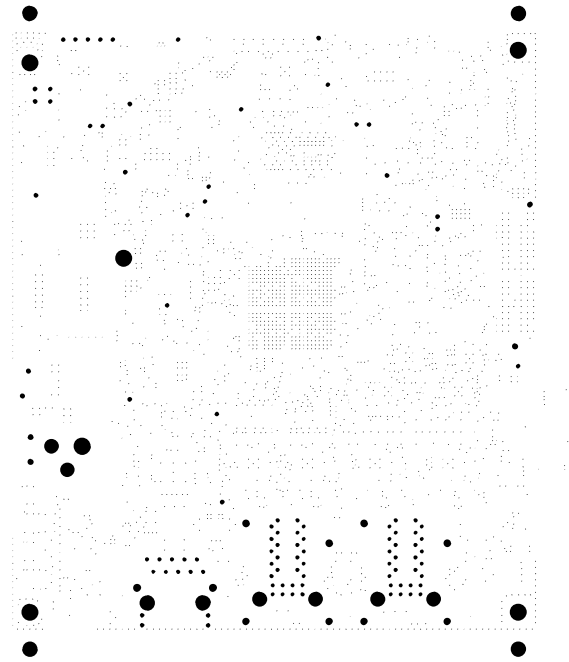
MISTRAL SOLUTIONS PVT LTD.
#60, ADARSH REGENT, 100' FEET RING ROAD,
DOMLUR EXTENSION, BANGALORE 560 071.

PCB,
K2G ICE 3N0003 PCB REV1.0D

APPROVALS		DATE	SIZE	DRAWING NO.	REV
DRAWN	JA	030317	C	FY160716000204	D
CHECKED	NP	030317	SCALE: NONE		SHEET 1 OF 15
APPROVED	AMB	030317	FILE NAME:		







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